Material declaration form

General Information

IPC	1752	Version	2
Form type*	Distribute		
Sectionals*	Material information	Subsectionals*	A-D
	Manufacturing information	*: Required Field*	

Supplier Information

Company name*	STMicroelectronics	Response Date*	2025-02-24
Contact name*	Refer to Supplier Comment section		Refer to Supplier Comment section
Contact phone*	Refer to Supplier Comment section	Contact email*	Refer to Supplier Comment section
Authorized representative*	MDG CHAMPION	Representative title	MDGMaterial Declaration champion
Representative phone*	Refer to Supplier Comment section	Representative email*	Refer to Supplier Comment section
Supplier comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty statement

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Legal statement

Supplier acceptance*	true	Legal declaration*	Standard

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr item number	Mfr item name	Version	Manufacturing site	date
STM32H563IGT6	261T*484XXXX	A	9991	2025-02-24
	Amount	Unit of measure	Unit type	ST ECOPACK grade
	1653	mg	Each	ECOPACK® 2

Manufacturing information				
J-STD-020 MSL rating	Classification temperature	Number of reflow cycles		
3	260	3		
Bulk solder termination	Terminal plating	Terminal base alloy	Comment	
Not Applicable	Tin (Sn), matte, annealed	Copper Alloy	0	
Package designator	Package size	Number of instances	Shape	
WLCSP	7x7	176	Bulk solder	
Comment	Package : 1T LQFP 176 24x24x1.4 0110489			

QueryList : RoHS Directive 2011/65/EU- 8 June 2011 – Annex II amended by Delegated Directive 2015/863 - 31 March 2015	**Response**
1 - Product(s) meets EU RoHS requirement without any exemptions	true
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	false
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	false

Exemption Id.	**Description**
,	

QueryList : REACH-21st January 2025				**Response**
QUERY				**Response**
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product
,	#N/A			

Material Composition Declaration : note : Substance present with less 0.001mg will not be declared in this document						**Mfr Item Name**	**261T*484XXXX**		1652.6534		6000000.0	1000000.0
Homogeneous material	**Material group**	**Mass**	**Unit of measure**	**Level**	**Substance category**	**Substance**	**CAS**	**Exempt**	**Mass**	**Unit of measure**	**Concentration in homogeneous material (ppm)**	**Concentration in product (ppm)**
Die or dies	M-011 Other inorganic materials	11.526	mg	supplier	die	Silicon (Si)	7440-21-3		11.006	mg	954831.4458	6659.427084
				supplier	metallization	Aluminium (Al)	7429-90-5		0.037	mg	3179.018478	22.1719151
				supplier	metallization	Copper (Cu)	7440-50-8		0.237	mg	20531.161	143.1936184
				supplier	metallization	Cobalt (Co)	7440-48-4		0.001	mg	66.22955163	0.461914898
				supplier	metallization	Tantalum (Ta)	7440-25-7		0.033	mg	2847.87072	19.86234061
				supplier	metallization	Tungsten (W)	7440-33-7		0.106	mg	9205.907676	64.20617081
				supplier	Passivation	Silicon Nitride	12033-89-5		0.027	mg	2384.263859	16.62893633
				supplier	Passivation	Silicon Oxide	7631-86-9		0.080	mg	6954.102921	48.50106428
Leadframe (C7025 + Ag + LLT R970)	Copper & its alloys	425.000	mg	supplier	Leadframe	Copper(Cu)	7440-50-8		385.178	mg	906300	233066.1171
				supplier	Leadframe	Nickle (Ni)	7440-02-0		12.920	mg	30400	7817.731392
				supplier	Leadframe	Silicon (Si)	7440-21-3		4.845	mg	11400	2931.649272
				supplier	Leadframe	Magnesium (Mg)	7439-95-4		1.233	mg	2900	745.7704289
				supplier	Leadframe	Silver (Ag)	7440-22-4		14.875	mg	35000	9000.67759
				supplier	Leadframe	Polyimide	Proprietary		2.380	mg	5600	1440.108414
				supplier	Leadframe	Poly–ethylene–terephthalate	25038-59-9		1.785	mg	4200	1080.081311
				supplier	Leadframe	NBR	Proprietary		0.595	mg	1400	360.0271036
				supplier	Leadframe	Bismaleimide	Proprietary		0.595	mg	1400	360.0271036
				supplier	Leadframe	Phenol resin	Proprietary		0.595	mg	1400	360.0271036
Glue (EN4900G)	Precious metals	2.532	mg	supplier	Glue or tape	Silver (Ag)	7440-22-4		1.912	mg	755000	1156.721702
				supplier	Glue or tape	Cresol Novolac Epoxy Resins	Proprietary		0.063	mg	25000	38.30204312
				supplier	Glue or tape	Diacrylate	Proprietary		0.215	mg	85000	130.2269466
				supplier	Glue or tape	Dicyclopentenyl group containing Acrylate	Proprietary		0.139	mg	55000	84.26449487
				supplier	Glue or tape	Butadiene copolymer	Proprietary		0.025	mg	10000	15.32081725
				supplier	Glue or tape	Polybutadiene epoxidized derivative	Proprietary		0.139	mg	55000	84.26449487
				supplier	Glue or tape	Peroxy Ketals	Proprietary		0.013	mg	5000	7.660408624
				supplier	Glue or tape	Substitutedalkoxyalkyl trimethoxysilane	Proprietary		0.013	mg	5000	7.660408624
				supplier	Glue or tape	Methacrylate multialkoxysubstitutedalkyl ester	Proprietary		0.013	mg	5000	7.660408624
Bonding Wire (Cu)	Precious metals	2.200	mg	supplier	Bonding wire	Copper (Cu)	7440-50-8		2.124	mg	965500	1285.266505
				supplier	Bonding wire	Palladium (Pd)	7440-05-3		0.068	mg	31000	41.26697221
				supplier	Bonding wire	Gold (Au)	7440-57-5		0.008	mg	3500	4.659174282
Encapsulation (EME-G631SH)	M-011 Other inorganic materials	1195.500	mg	supplier	Molding Compound	2,2'-((3,3',5,5'-Tetramethyl-(1,1'-biphenyl)-4,4'-diy	85954-11-6		47.820	mg	40000	28935.28755
				supplier	Molding Compound	Epoxy resin	Proprietary		23.910	mg	20000	14467.64378
				supplier	Molding Compound	Phenol Resin	Proprietary		89.663	mg	75000	54253.66416
				supplier	Molding Compound	Silica(Amorphous) A	60676-86-0		848.207	mg	709500	513239.663
				supplier	Molding Compound	Silica(Amorphous) B	7631-86-9		179.325	mg	150000	108507.3283
				supplier	Molding Compound	Carbon black	1333-86-4		6.575	mg	5500	3978.602038
Plating (Sn)	M-011 Other inorganic materials	15.895	mg	supplier	Matte Sn	Tin (Sn)	7440-31-5		15.893	mg	999900	9616.905124
				supplier	Matte Sn	Impurities	Proprietary		0.002	mg	100	0.961786691